



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



EPCDESIGNTOOL_LG-EM

Mechanical Die for Electromigration Testing

EPCDESIGNTOOL_LG-EM are sized equivalent to EPC device [EPC2001C](#) with die size 4.1 mm x 1.6 mm.

These devices have internal metal layers shorted for electromigration reliability testing.

Figure 1: Die Photo for EPCDESIGNTOOL_LG-EM

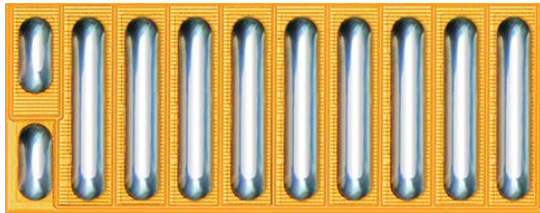
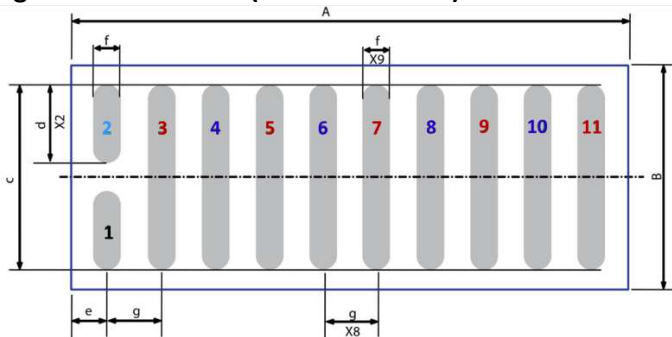


Figure 2: Die Outline (Solder Bar View)



DIM	MICROMETERS		
	MIN	Nominal	MAX
A	4075	4105	4135
B	1602	1632	1662
c	1379	1382	1385
d	577	580	583
e	235	250	265
f	195	200	205
g	400	400	400

Pad 1 is Gate;

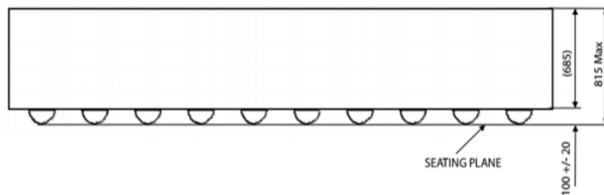
Pads 3, 5, 7, 9, 11 are Drain

Pads 4, 6, 8, 10 are Source

Pad 2 is Substrate

NOTE: Drain and Source are internally shorted at Metal 1 to create a metal resistor

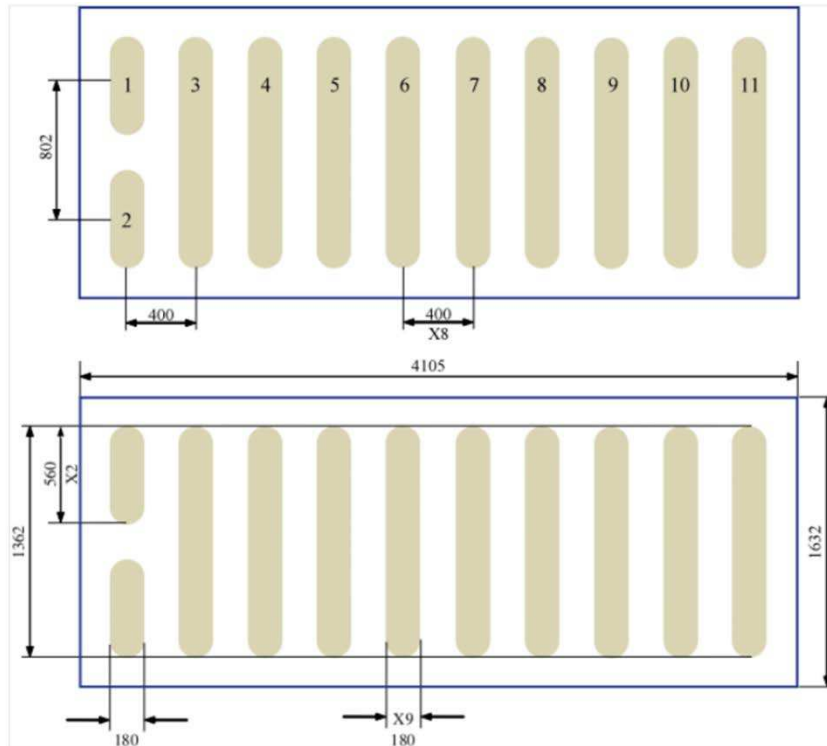
Figure 3: Side View



EPCDESIGNTOOL_LG-EM Mechanical Die for Electromigration Testing

Figure 4: Recommended Land Pattern (units in μm)

Land pattern is solder mask defined. Solder mask opening is $180\ \mu\text{m}$. Recommended stencil should be 4mil ($100\ \mu\text{m}$) thick, must be laser cut, Stencil opening can be per the bump drawing.



Pad 1 is Gate;

Pads 3, 5, 7, 9, 11 are Drain

Pads 4, 6, 8, 10 are Source

Pad 2 is Substrate

Additional assembly resources available at epc-co.com/epc/DesignSupport/AssemblyBasics.aspx

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